



I'm not robot



I am not robot!

The product provides rapid bonding of a wide range of materials, including metals, plastics. The gel consistency prevents adhesive flow even on
ver pense temperatures are E can also be dispensed using p. for dispensing by pin d adhesive can be cleaned from the board with isopropanol,
MEK or este. t thread free. Americas Europe Asia + + + agement Blind Holes, apply several drops of the product down the internal threads to the
bott. hear strength. nd elastomers. itive displacement pump product is not recommend. of the Sealing Applications, apply a ° bead of product to
the leading threads of the male fitting, leaving the fir. Force the ence" E® TM is designed for the assembly of difficult-to-bond materials which
require uniform stress distribution and strong tension and/or.